Figures

Figure 1

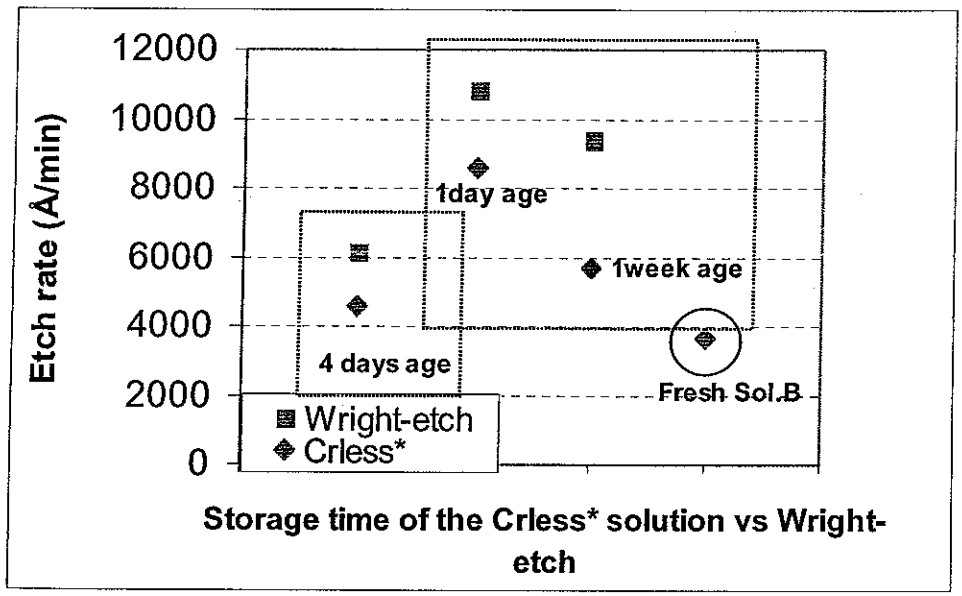


Figure 2

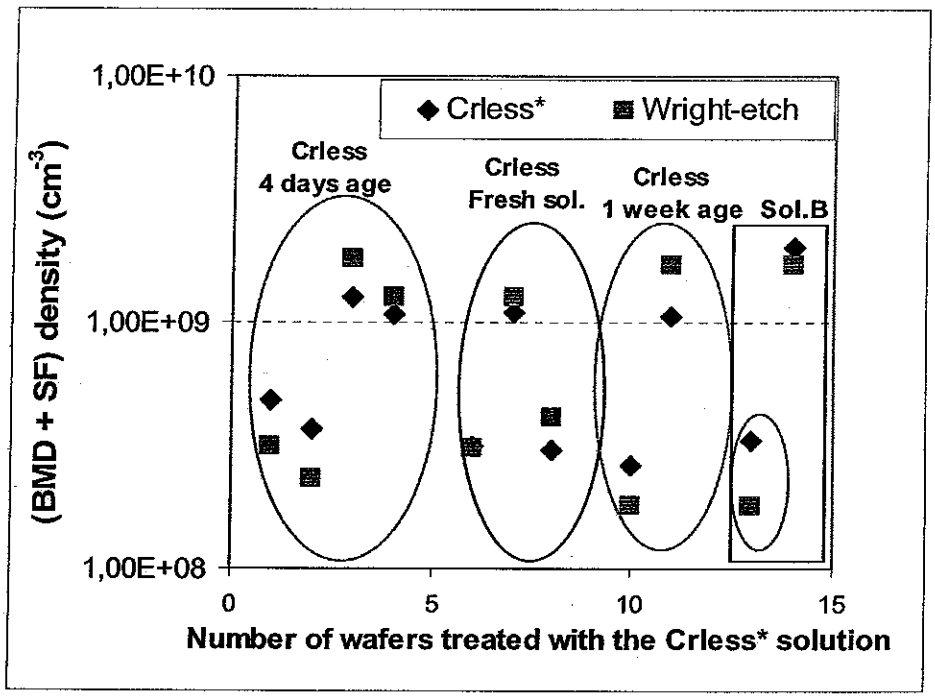


Figure 3

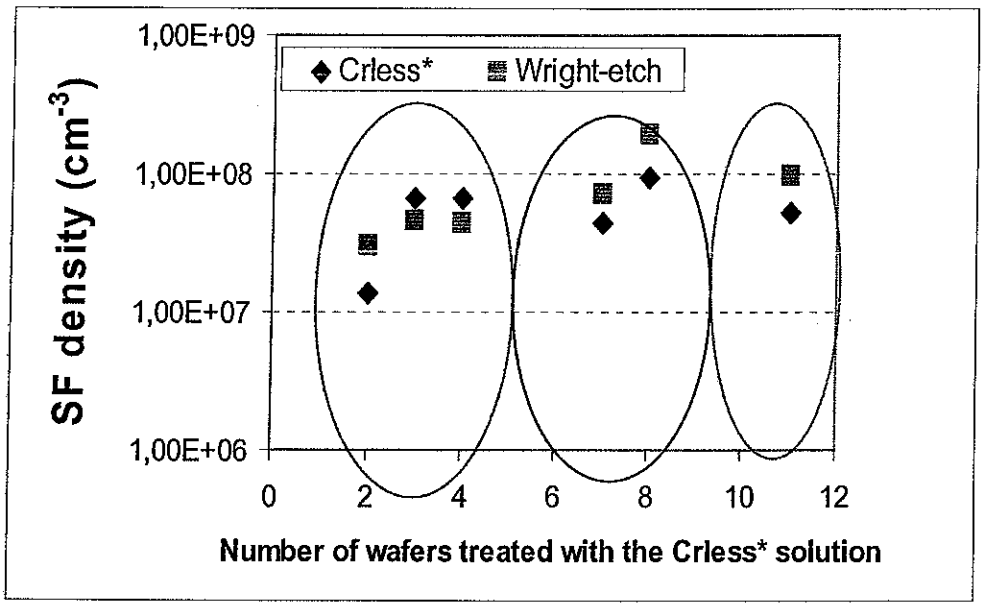

1,00E+09
1,00E+08
1,00E+07
1,00E+06
SF density (cm-3)
Crless*
Wright-etch
0
2
4
6
8
10
12
Number of wafers treated with the Crless* solution

Figure 4

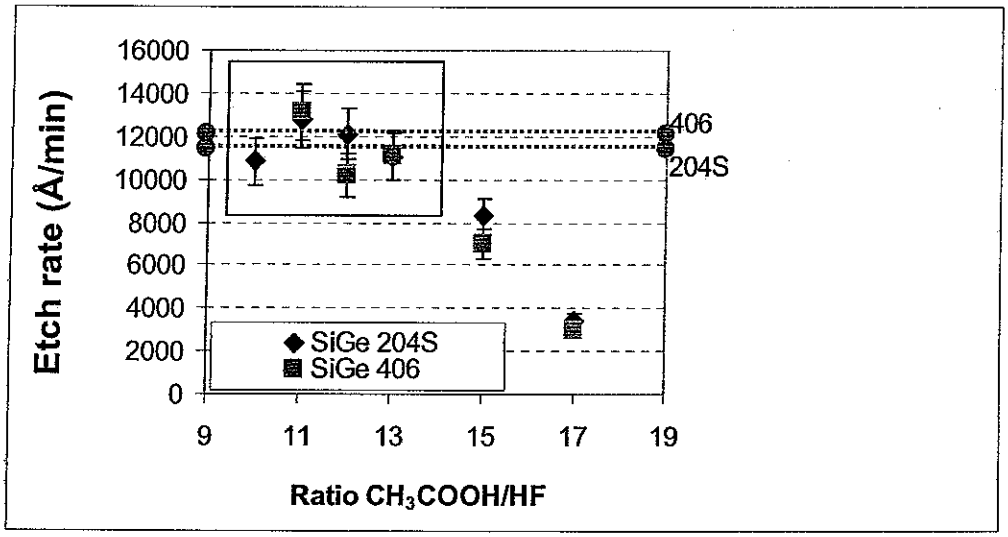

Etch rate (Å/min)
16000
14000
12000
10000
8000
6000
4000
2000
0
9
11
13
15
17
19
406
204S
SiGe 204S
SiGe 406
Ratio CH3COOH/HF

Figure 5

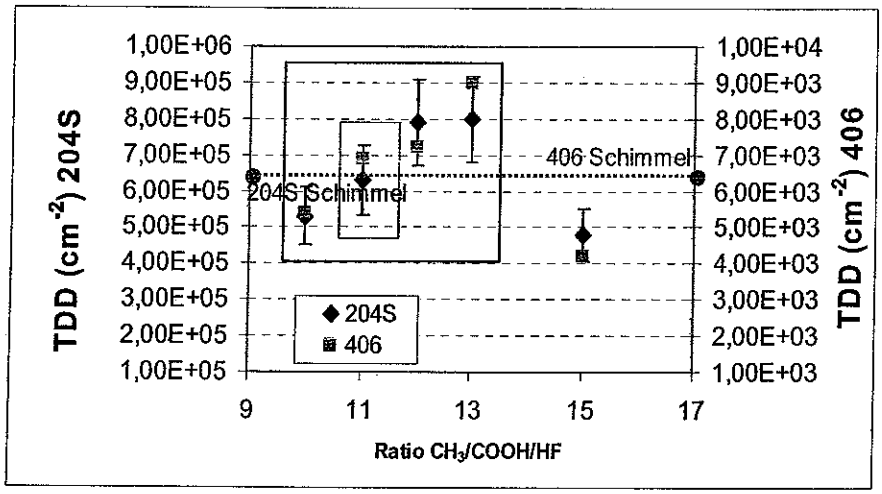


Figure 6

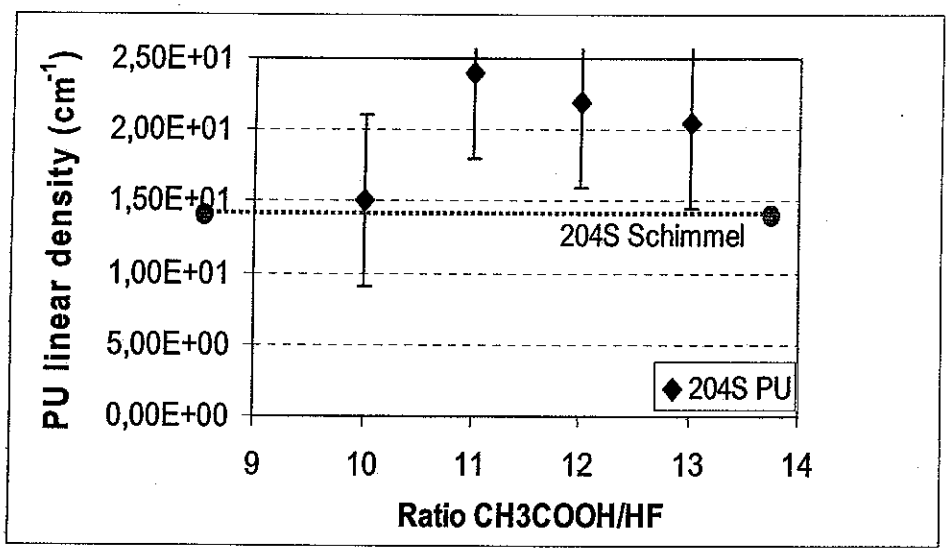
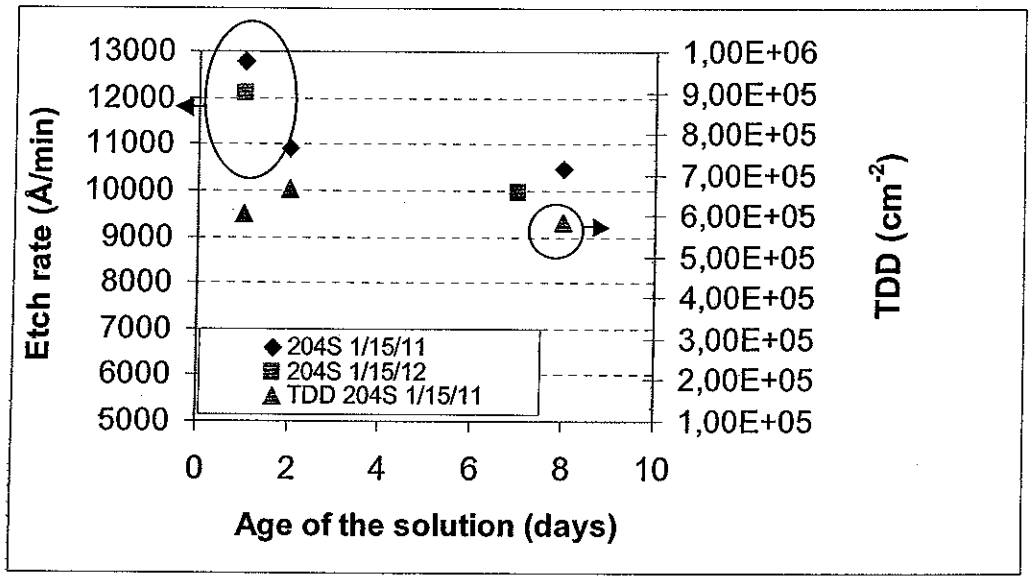


Figure 7


13000
12000
11000
10000
9000
8000
7000
6000
5000
Etch rate (Å/min)
1,00E+06
9,00E+05
8,00E+05
7,00E+05
6,00E+05
5,00E+05
4,00E+05
3,00E+05
2,00E+05
1,00E+05
TDD (cm-2)
204S 1/15/11
204S 1/15/12
TDD 204S 1/15/11
0
2
4
6
8
10
Age of the solution (days)